



Material Content Data Sheet



Sales Product Name				IPI200N25N3 G		Issued		25. September 2017	
MA#				MA000812204					
Package				PG-TO262-3-1		Weight*		1581.70 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	17.562	1.11	1.11	11103	11103	
leadframe	non noble metal	iron	7439-89-6	0.851	0.05		538		
	inorganic material	phosphorus	7723-14-0	0.255	0.02		161		
	non noble metal	copper	7440-50-8	849.682	53.72	53.79	537195	537895	
wire	non noble metal	aluminium	7429-90-5	11.640	0.74	0.74	7359	7359	
encapsulation	organic material	carbon black	1333-86-4	8.546	0.54		5403		
	plastics	epoxy resin	-	94.007	5.94		59434		
	inorganic material	silicondioxide	60676-86-0	467.184	29.54	36.02	295368	360205	
leadfinish	non noble metal	tin	7440-31-5	15.198	0.96	0.96	9608	9608	
plating	non noble metal	nickel	7440-02-0	0.228	0.01		144		
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	1	144	
solder	noble metal	silver	7440-22-4	0.255	0.02		161		
	non noble metal	tin	7440-31-5	0.204	0.01		129		
	non noble metal	lead	7439-92-1	9.743	0.62	0.65	6160	6450	
heatspreader	inorganic material	phosphorus	7723-14-0	0.032	0.00		20		
	non noble metal	iron	7439-89-6	0.106	0.01		67		
	non noble metal	copper	7440-50-8	106.210	6.71	6.72	67149	67236	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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